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AMENDMENT JDER 37 CFR 1.116 EXPEDITED PROCEDURE -EXAMINING GROUP 1762

AUG 1 6 2000 ON TRADE WONSEND and TOWNSEND and CREW LLP

PATENT AM524R1/T289 016301-028900

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

KATSUYUKI MUSAKA et al.

Application No.: 09/187,551

Filed: November 5, 1998

For: METHOD FOR FORMING A THIN

FILM FOR A SEMICONDUCTOR

DEVICE

Examiner: Marianne Padgett

AMENDMENT UNDER 37 CFR 1.116 EXPEDITED PROCEDURE EXAMINING

GROUP 1762



Box AF

Assistant Commissioner for Patents Washington, D.C. 20231

Sir:

In response to the Final Office Action mailed June 12, 2001, please reconsider this application in view of the following remarks.

IN THE CLAIMS:

The claims as previously amended are reproduced below for the Examiner's convenience and reference.

1. A method of forming a conformal thin film of silicon oxide on a substrate having spaced conductive lines thereon comprising the steps of:

mounting a substrate onto a substrate support in a vacuum chamber;

forming a plasma in the vacuum chamber in a region above the substrate by means of an electrical power source from a reaction gas comprising a mixture of tetraethylorthosilicate and a fluorine-containing halocarbon gas selected from the group consisting of $[CX_4]$ CY_4 and CX_3 -

Please type a plus sign (+) inside this ox -

PTO/SB/21 (08-00)

Approved for use through 10/31/2002. OMB 0651-0031 U.S. Patent and Trademark Office: U.S. DEPARTMENT OF COMMERCE

09/187,551

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Application Number

TRANSMITTAL FORM

(to be used for all correspondence after initial filing)

Filing Date November 5, 1998 **First Named Inventor** Musaka, Katsuyuki **Group Art Unit** 1762 **Examiner Name** Marianne Padgett

Total Number of Pages in This Submission **Attorney Docket Number** AM524R1T289

ENCLOSURES (check all that apply)				
Fee Transmittal Form		Assignment Papers (for an Application)		After Allowance Communication to Group
Fee Attached		☐ Drawing(s)		Appeal Communication to Board of Appeals and Interferences
Amendment / Response		Licensing-related Papers		Appeal Communication to Group (Appeal Notice, Brief, Reply Brief)
After Final		Petition Routing Slip (PTO/SB/69) and Accompanying Petition		Proprietary Information
Affidavits/declaration(s)		Petition to Convert to a Provisional Application		Status Letter
Extension of Time Request		Power of Attorney, Revocation Change of Correspondence Address		Other Enclosure(s) (please identify below):
Express Abandonment Request		☐ Terminal Disclaimer ☐ Request for Refund		Two Return Postcards
☐ Information Disclosure Statement		CD, Number of CD(s)		
Certified Copy of Priority Document(s)		Remarks The Commissioner is authorized to charge any additional fees to Deposit Account 20-1430.		
Response to Missing Parts/ Incomplete Application		Cy Zoon		
Response to Missing Parts under 37 CFR 1.52 or 1.53				
SIGNATURE OF APPLICANT, ATTORNEY, OR AGENT				
Firm	Townsend and Townsend and Crew LLP			
and Individual name	Chun-Pok Leung Reg No. 41,405			
Signature	8-12-01			
Date 8-12-		-01		
CERTIFICATE OF MAILING				

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